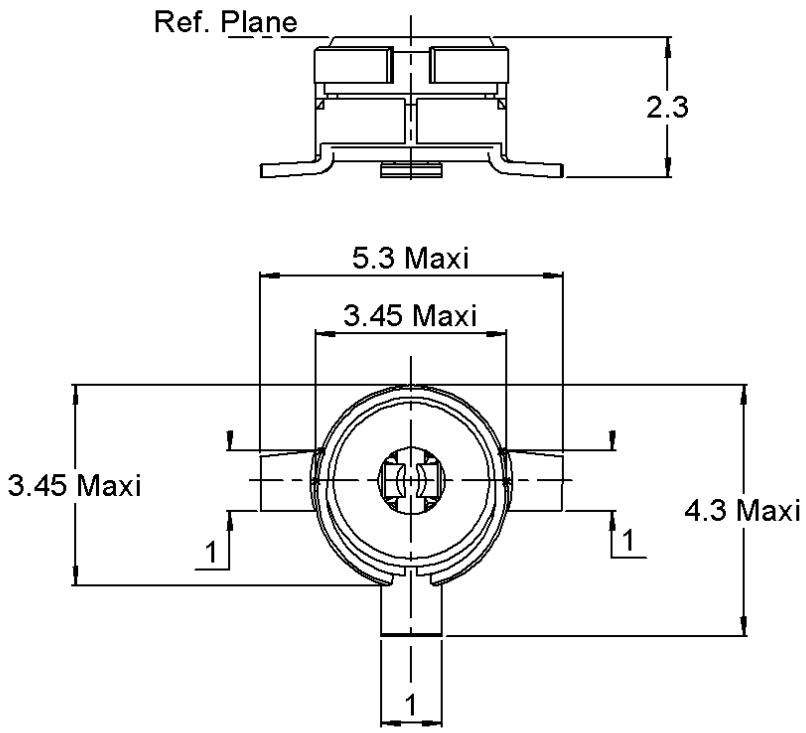
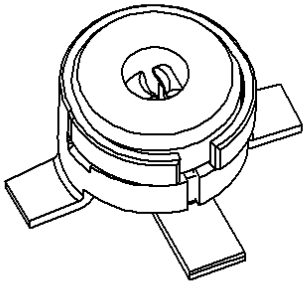
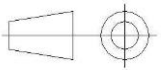
PAGE **1/5**	ISSUE **03-02-17B**	SERIES **MMS**	PART NUMBER **R209408012**





Scale: 1/1

All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
Body	**PHOSPHOR BRONZE**	**GOLD 0.2 OVER NICKEL 2**
Center contact	**BERYLLIUM COPPER**	**GOLD 0.2 OVER TIN NICKEL 2**
Outer contact		
Insulator	**PTFE**	
Gasket	**-**	
Others parts	**-**	-
-	**-**	-
-	**-**	-

PACKAGING

Standard	Unit	Other
100	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance		**50**	Ω
Frequency		**0-6**	GHz
VSWR	* +	**0,0000**	x F(GHz) Maxi
Insertion loss		**	√F(GHz) dB Maxi
RF leakage	- (	**NA**	- F(GHz)) dB Maxi
Voltage rating		**50**	Veff Maxi
Dielectric withstanding voltage		**250**	Veff mini
Insulation resistance		**500**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**NA**	N mini
Axial force – Opposite end	**NA**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**50**	Cycles mini
Weight	**0,0590**	g

ENVIRONMENTAL

Operating temperature	**-40/+125**	°C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

SPECIFICATION

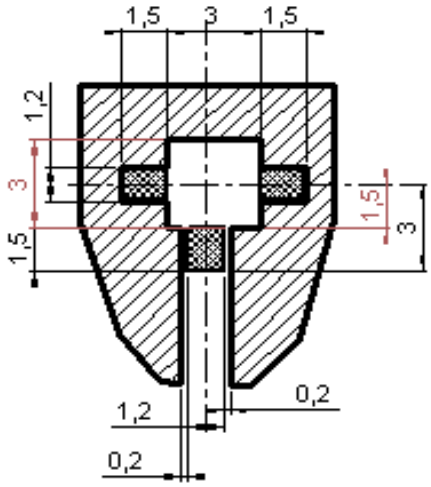
OTHER CHARACTERISTICS

Assembly instruction:

Others:
***1.2 à 2GHz/Avg 1,07 **Max 0.07/Avg 0.06**

MMS SERIES – INFORMATION

Coplanar line : Ground and signal are on the same side . Thicknass of PCB : 1mm
The material of PCB is glass-epoxy composite. (Er = 4.8)
The sold er resist should be printed except for the land pattern on the PCB.

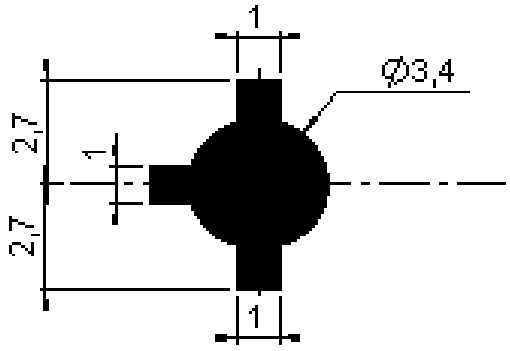


Pattern

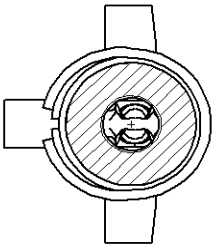
Land for solder paste

SHADOW OF MMS RECEPTACLE

FOR VIDEO CAMERA



ASPIRATION AREA



ASPIRATION AREA

SOLDER PROCEDURE

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.

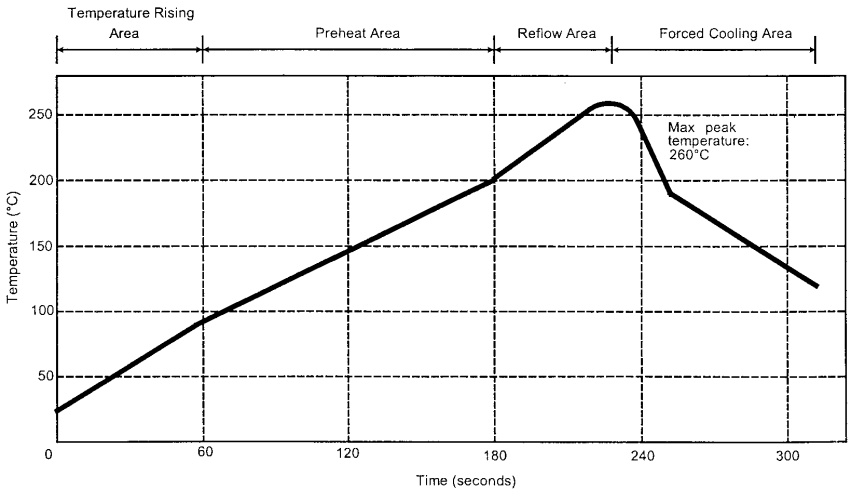
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

3. Soldering by infra-red reflow.

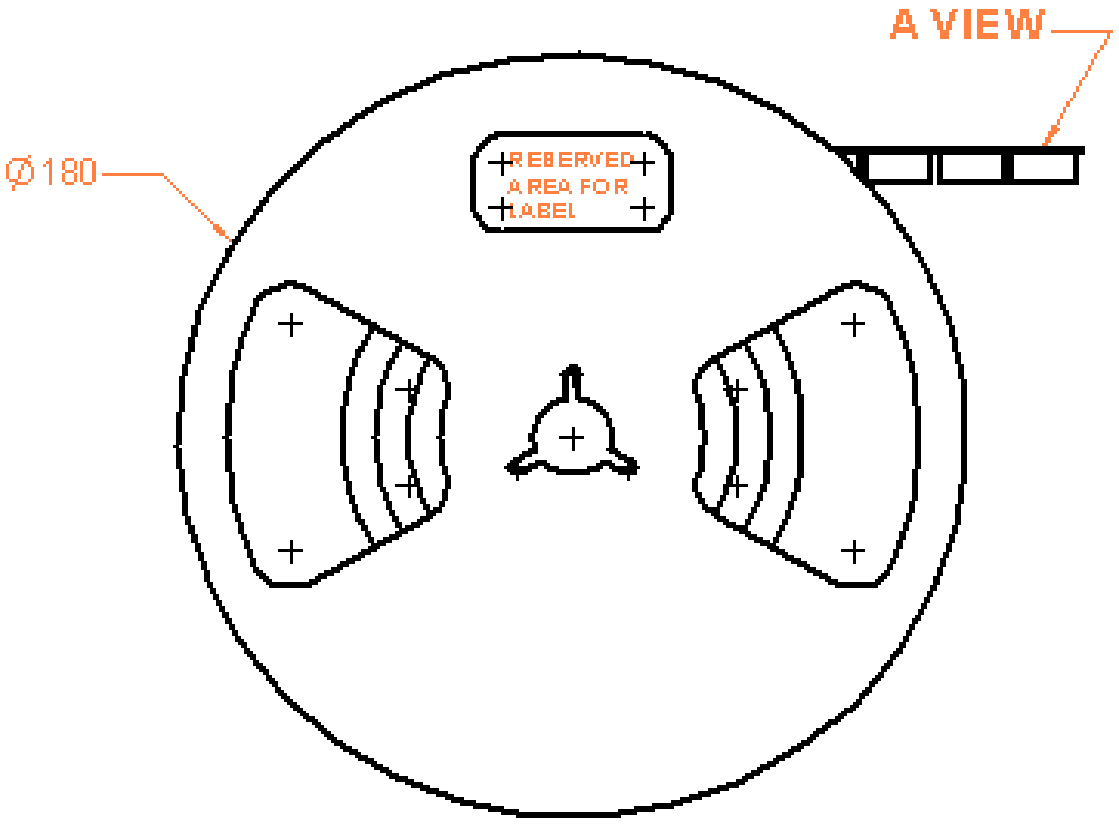
4. Cleaning of printed circuit boards.

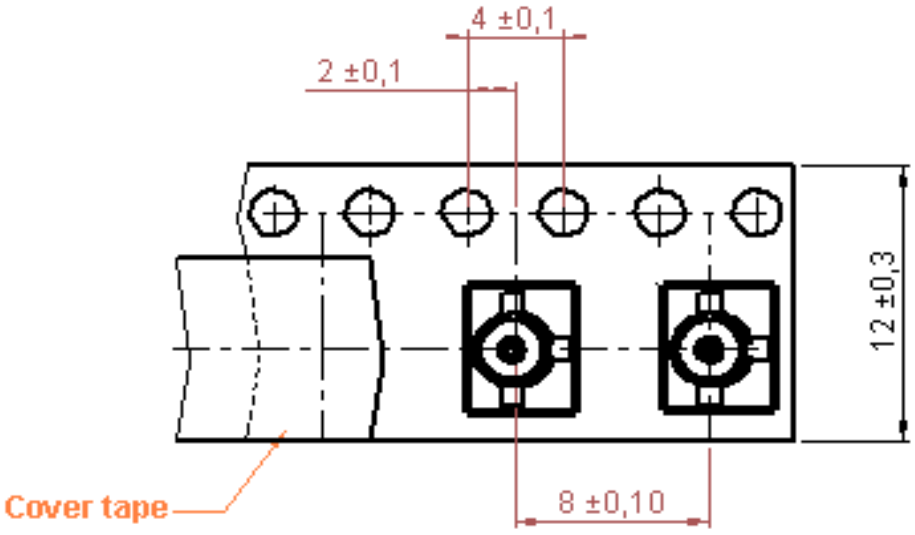
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec





A VIEW (scale : 4)